

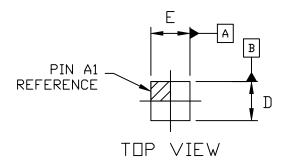




WLCSP4, 0.64x0.64x0.33

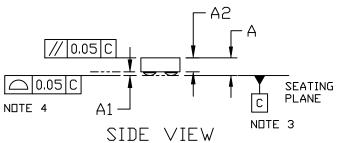
CASE 567JZ **ISSUE B**

DATE 16 MAY 2022

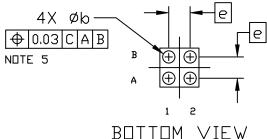


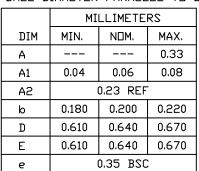
NOTES:

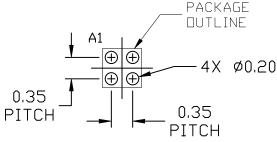
- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPERICAL CROWNS OF THE SOLDER BUMPS.
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- DIMENSION & IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER PARALLEL TO DATUM C.



// 0.0	05 C		_ 	Α	
○ 0.05 C N□TE 4	A1 -	VIEW	A	C NDTE	SEATING PLANE 3







GENERIC MARKING DIAGRAM*



= Specific Device Code Х

Μ = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "=", may or may not be present. Some products may not follow the Generic Marking.

RECOMMENDED MOUNTING FOOTPRINT * (NSMD PAD TYPE)

For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, SILDERRM/D.

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DESCRIPTION:	WLCSP4, 0.64X0.64x0.33		PAGE 1 OF 1		

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